

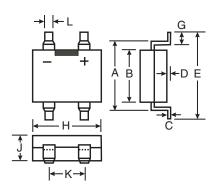
0.8A SURFACE MOUNT GLASS PASSIVATED BRIDGE **RECTIFIER**

Features

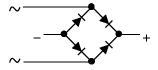
- Glass Passivated Die Construction
- Low Forward Voltage Drop
- Surge Overload Rating to 30A Peak
- Ideally Suited for Automatic Assembly
- Miniature Package Saves Space on PC Boards
- UL Listed Under Recognized Component Index, File Number E94661
- Lead Free Finish, RoHS Compliant (Note 3)

Mechanical Data

- Case: MiniDIP
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture sensitivity: Level 1 per J-STD-020C
- Terminals: Finish Tin. Plated Leads, Solderable per MIL-STD-202, Method 208 @3)
- Polarity: As Marked on Case
- Marking: Type Number, Date Code & Polarity Markings
- Weight: 0.125 grams (approximate)



MiniDIP							
Dim	Min	Max					
Α	5.43	5.75					
В	3.6	4.0					
С	0.15	0.35					
D	0.05	0.20					
E	_	7.0					
G	0.70	1.10					
Н	4.5	4.9					
J	2.3	2.7					
K	2.3	2.7					
L	0.50	0.80					
All Dimensions in mm							



Equivalent Schematic

Maximum Ratings and Electrical Characteristics @ T_A = 25°C unless otherwise specified

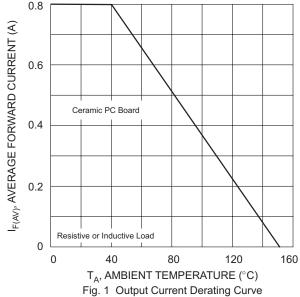
Single phase, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	HD01	HD02	HD04	HD06	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RMM} V _{RWM} V _{DC}	100	600	V			
RMS Reverse Voltage	V _{RMS}	70	140	280	420	V	
Average Forward Rectified Current (Note 1) T _A = @ 40°C	Io	0.8					
Non-Repetitive Peak Forward Surge Current, 8.3 ms Single half-sine-wave Superimposed on Rated Load	I _{FSM}	30					
Instantaneous Voltage Drop @ 0.4A (per element)	VF	1.0					
$ \begin{array}{llllllllllllllllllllllllllllllllllll$	I _R	5.0 500				μА	
Typical Total Capacitance (per element) (Note 2)	C _T	10					
Typical Thermal Resistance, Junction to Ambient (Note 1)	R _θ JA	75					
Operating and Storage Temperature Range	T _j , T _{STG}	-55 to +150					

Notes:

- 1. Mounted on Ceramic PC Board.
- 2. Measured at 1.0 MHz and Applied Reverse Voltage of 4.0 V.
- 3. RoHS revision 13.2.2003. Glass and High Temperature Solder Exemptions Applied, see EU Directive Annex Notes 5 and 7.





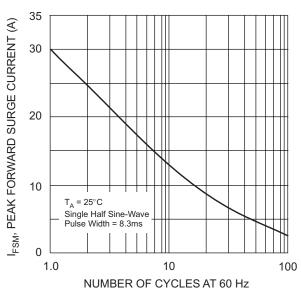
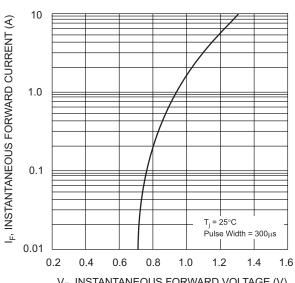


Fig. 3 Maximum Peak Forward Surge Current (per element)



 V_{F} , INSTANTANEOUS FORWARD VOLTAGE (V) Fig. 2 Typical Forward Characteristics (per element)

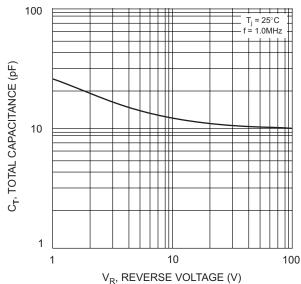
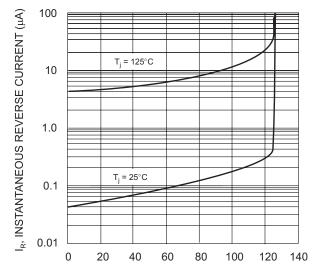


Fig. 4 Typical Total Capacitance (per element)



PERCENT OF RATED PEAK REVERSE VOLTAGE (%) Fig. 5 Typical Reverse Characteristics (per element)



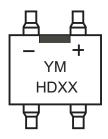
Ordering Information (Note 4)

Device*	Packaging	Shipping		
HDxx-T	MiniDIP	3K/Tape & Reel, 13-inch		

^{*}xx = Device type, e.g. HD02-T or HD04-T, etc.

Notes: 4. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



YM = Date code marking Y = Last digit of the year M = See Month/Code Table Below HDXX = Product type marking code, Ex: HD04

Month	Jan	Feb	March	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

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